

COMPOUND FIELD EFFECT TRANSISTOR ARRAY

μ PA1550

N-CHANNEL POWER MOS FET ARRAY FOR SWITCHING

 μ PA1550 is a N-channel vertical power MOS FET and this switching device is available for direct drive by output of 5 V power supply IC.

This device features low on-resistance and excellent switching characteristic, and is ideal for control of devices such as mortars, solenoid, or ramp.

FEATURES

- Gate drive available at logic level (V_{GS} = 4 V)
- · High current capacity and low on-resistnace

 $I_{D(pulse)} = \pm 20 \text{ A}$

 $R_{DS(on)} = 0.09 \Omega TYP. @V_{GS} = 10 V$

 $R_{DS(on)} = 0.11 \Omega TYP. @V_{GS} = 4 V$

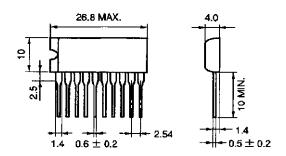
- Easy to mount the printing board due to 2.54 mm (0.1 inch) interval of lead pins
- Small dimension and no electrode exposure except lead pins enable the high density mounting.

ORDERING INFORMATION

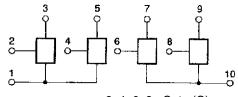
Part Number	Package	Quality
μPA1550H	10-pin SIP	Standard

Please refer to "Quality Grades on NEC Semiconductor Devices" (Document No. C11531E) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

PACKAGE DRAWING (UNIT: mm)

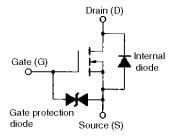


ELECTRODE CONNECTION



2, 4, 6, 8 : Gate (G) 3, 5, 7, 9 : Drain (D) 1, 10 : Source (S)

INTERNAL EQUIVALENT CIRCUIT



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ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

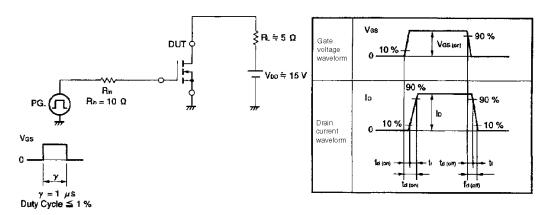
Parameter	Symbol	Conditions	Ratings	Unit
Drain to source voltage	VDSS	V _G s = 0	30	V
Gate to source voltage	Vgss	V _{DS} = 0	±20	V
Drain current (DC)	I _{D(DC)}	Tc = 25°C	±5	A/unit
Drain current (pulse)	ID(pulse)	PW \leq 10 μ s duty cycle \leq 1 %	±20	A/unit
Total power dissipation	P _{T1} *	Tc = 25°C	3.5	W
Total power dissipation	P _{T2} *	T _a = 25°C	28	W
Channel temperature	Tch		150	°C
Storage temperature	T _{stg}		-55 to +150	°C

^{*} When all 4 elements are ON.

ELECTRICAL CHARACTERISTICS (VCC = 5V, Ta = 25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Drain cutoff current	IDSS	V _{DS} = 30 V, V _{GS} = 0 V			10	μΑ
Gate leakage current	lgss	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
Gate cutoff voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	0.8		2.5	V
Forward transfer admittance	y _{ts}	V _{DS} = 10 V, I _D = 3 A	4.0	5.0		S
Drain to source on-state resistance	RDS(on)1	Vgs = 10 V, Ib = 3 A		90	100	mΩ
Drain to source on-state resistance	RDS(on)2	V _{GS} = 4 V, I _D = 3 Å		110	150	mΩ
Input capacitance	Ciss	V _{DS} = 10 V		900		pF
Output capacitance	Coss	V _{GS} = 0 V		400		pF
Return capacitance	Crss	f = 1 MHz		100		pF
Turn-on delay time	t _{d(on)}	$\begin{split} &\text{ID} = 3 \text{ A} \\ &\text{VGS(on)} = 10 \text{ V} \\ &\text{VDD} = 5 \Omega \\ &\text{RL} = 5 \Omega, \\ &\text{Rin} = 10 \Omega \\ &\text{Refer to the test circuit.} \end{split}$		10		ns
Rise time	tr			40		ns
Turn-off delay time	td(off)			110		ns
Fall time	t _f			30		ns

TEST CIRCUIT DIAGRAM: SWITCHING TIME



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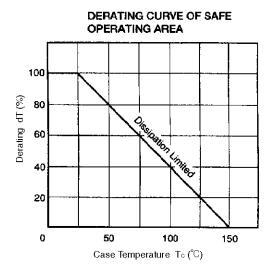
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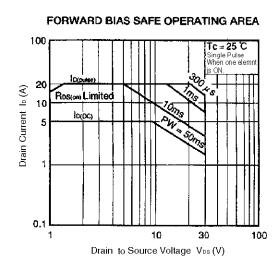
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TYPICAL CHARACTERISTICS (Ta = 25°C)

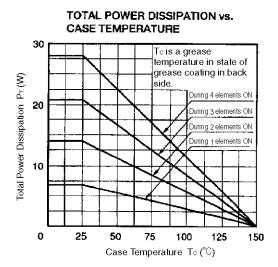




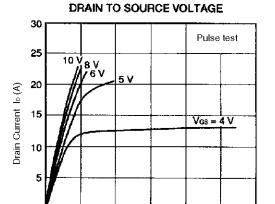
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE Each element is regarded NEC as the seme dissipation. μPA1550 lead pin Fotal Power Dissipation P⊤(W) - Printing board During 4 elements ON During 3 elements ON During 2 elements ON During 1 elements ON 0 25 75 50 100 125 150

Ambient Temperature Ta (°C)

DRAIN CURRET vs.

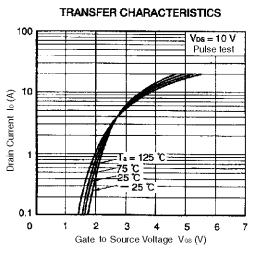


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Drain to Source Voltage VDS (V)

0

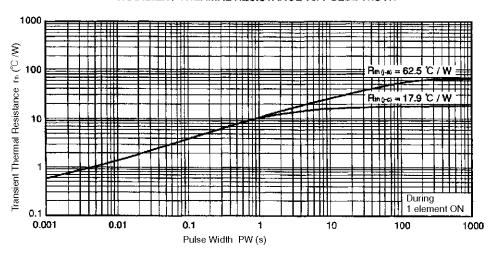


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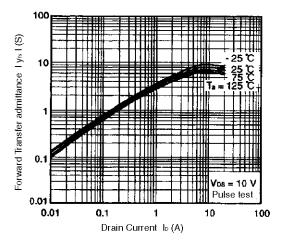
Data Sheet G16142EJ1V0DS 3

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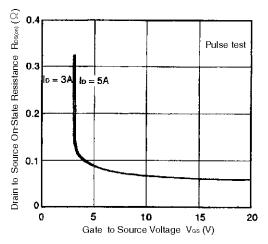
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



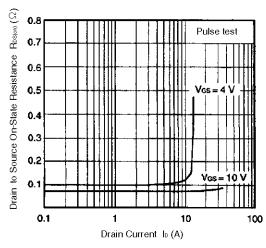
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



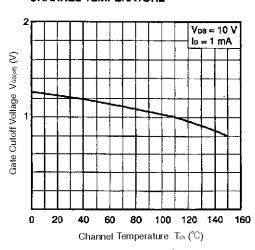
DRAIN TO SOURCE ON STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



DRAIN TO SOURCE ON STATE RESISTANCE vs. DRAIN CURRENT



GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



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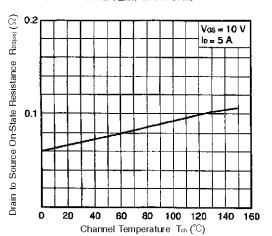
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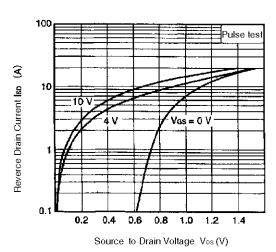
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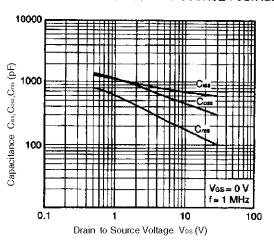
DRAIN TO SOURCE ON - STATE RESISTANCE vs. CHANNEL TEMPERATURE



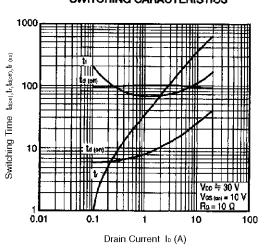
BODY DIODE FORWARD VOLTAGE



CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



SWITCHING CARACTERISTICS



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μ**PA**1550



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